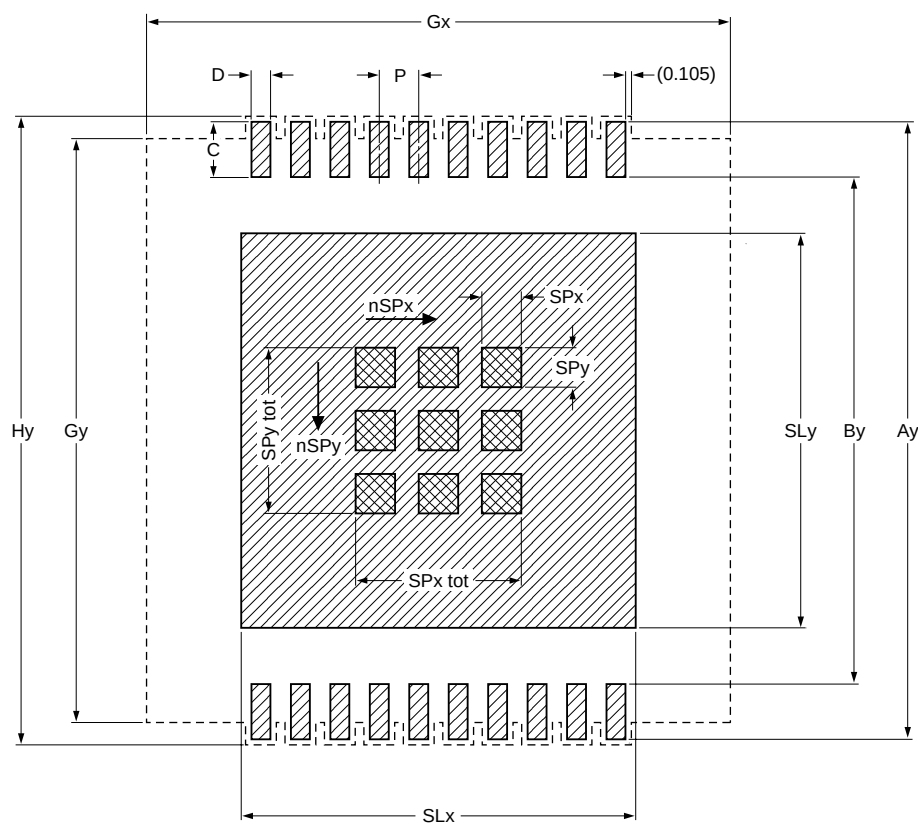


Footprint information for reflow soldering of HVSON10 package

SOT650-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

DIMENSIONS in mm

P	Ay	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hy
0.500	4.000	2.200	0.900	0.240	2.400	1.500	1.400	0.650	0.550	0.650	3.300	3.300	4.250

nSPx	nSPy
2	1